

MOSFET

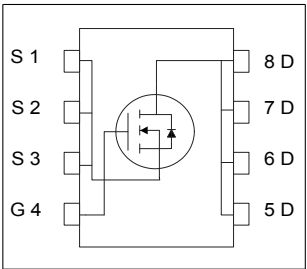
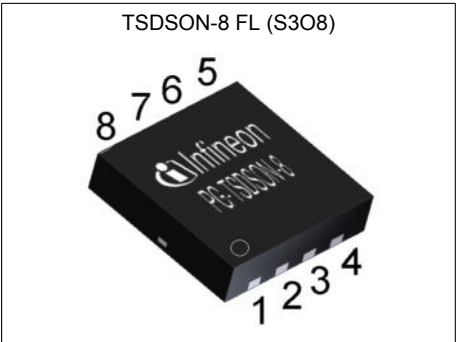
OptiMOS™ Power-MOSFET, 30 V

Features

- Optimized for high performance Buck converter (Server,VGA)
- Very Low FOM<sub>QOSS</sub> for High Frequency SMPS
- Low FOM<sub>SW</sub> for High Frequency SMPS
- Excellent gate charge x  $R_{DS(on)}$  product (FOM)
- Very low on-resistance  $R_{DS(on)}$  @  $V_{GS}=4.5\text{ V}$
- 100% avalanche tested
- Superior thermal resistance
- N-channel
- Qualified according to JEDEC<sup>1)</sup> for target applications
- Pb-free lead plating; RoHS compliant
- Halogen-free according to IEC61249-2-21

Table 1 Key Performance Parameters

| Parameter        | Value | Unit |
|------------------|-------|------|
| $V_{DS}$         | 30    | V    |
| $R_{DS(on),max}$ | 1.9   | mΩ   |
| $I_D$            | 149   | A    |
| $Q_{OSS}$        | 25    | nC   |
| $Q_G(0V..10V)$   | 44    | nC   |



RoHS

| Type / Ordering Code | Package        | Marking | Related Links |
|----------------------|----------------|---------|---------------|
| BSZ019N03LS          | PG-TSDSON-8 FL | 019N03L | -             |

<sup>1)</sup> J-STD20 and JESD22

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## 1 Maximum ratings

at  $T_A=25\text{ °C}$ , unless otherwise specified

**Table 2 Maximum ratings**

| Parameter                                     | Symbol            | Values |      |                              | Unit | Note / Test Condition                                                                                                                                                                                                                                         |
|-----------------------------------------------|-------------------|--------|------|------------------------------|------|---------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
|                                               |                   | Min.   | Typ. | Max.                         |      |                                                                                                                                                                                                                                                               |
| Continuous drain current <sup>1)</sup>        | $I_D$             | -      | -    | 149<br>94<br>130<br>82<br>22 | A    | $V_{GS}=10\text{ V}$ , $T_C=25\text{ °C}$<br>$V_{GS}=10\text{ V}$ , $T_C=100\text{ °C}$<br>$V_{GS}=4.5\text{ V}$ , $T_C=25\text{ °C}$<br>$V_{GS}=4.5\text{ V}$ , $T_C=100\text{ °C}$<br>$V_{GS}=4.5\text{ V}$ , $T_A=25\text{ °C}$ , $R_{thJA}=60\text{ K/W}$ |
| Pulsed drain current <sup>2)</sup>            | $I_{D,pulse}$     | -      | -    | 596                          | A    | $T_C=25\text{ °C}$                                                                                                                                                                                                                                            |
| Avalanche current, single pulse <sup>3)</sup> | $I_{AS}$          | -      | -    | 20                           | A    | $T_C=25\text{ °C}$                                                                                                                                                                                                                                            |
| Avalanche energy, single pulse                | $E_{AS}$          | -      | -    | 150                          | mJ   | $I_D=20\text{ A}$ , $R_{GS}=25\text{ }\Omega$                                                                                                                                                                                                                 |
| Gate source voltage                           | $V_{GS}$          | -20    | -    | 20                           | V    | -                                                                                                                                                                                                                                                             |
| Power dissipation                             | $P_{tot}$         | -      | -    | 69<br>2.1                    | W    | $T_C=25\text{ °C}$<br>$T_A=25\text{ °C}$ , $R_{thJA}=60\text{ K/W}$                                                                                                                                                                                           |
| Operating and storage temperature             | $T_J$ , $T_{stg}$ | -55    | -    | 150                          | °C   | IEC climatic category;<br>DIN IEC 68-1: 55/150/56                                                                                                                                                                                                             |

## 2 Thermal characteristics

**Table 3 Thermal characteristics**

| Parameter                                                      | Symbol     | Values |      |      | Unit | Note / Test Condition |
|----------------------------------------------------------------|------------|--------|------|------|------|-----------------------|
|                                                                |            | Min.   | Typ. | Max. |      |                       |
| Thermal resistance, junction - case                            | $R_{thJC}$ | -      | -    | 1.8  | K/W  | -                     |
| Device on PCB,<br>6 cm <sup>2</sup> cooling area <sup>4)</sup> | $R_{thJA}$ | -      | -    | 60   | K/W  | -                     |

<sup>1)</sup> Rating refers to the product only with datasheet specified absolute maximum values, maintaining case temperature at 25°C. For higher case temperature please refer to Diagram 2. De-rating will be required based on the actual environmental conditions.

<sup>2)</sup> See Diagram 3 for more detailed information

<sup>3)</sup> See Diagram 13 for more detailed information

<sup>4)</sup> Device on 40 mm x 40 mm x 1.5 mm epoxy PCB FR4 with 6 cm<sup>2</sup> (one layer, 70 µm thick) copper area for drain connection. PCB is vertical in still air.

### 3 Electrical characteristics

at  $T_j=25\text{ °C}$ , unless otherwise specified

**Table 4 Static characteristics**

| Parameter                        | Symbol        | Values |            |            | Unit          | Note / Test Condition                                                                                                               |
|----------------------------------|---------------|--------|------------|------------|---------------|-------------------------------------------------------------------------------------------------------------------------------------|
|                                  |               | Min.   | Typ.       | Max.       |               |                                                                                                                                     |
| Drain-source breakdown voltage   | $V_{(BR)DSS}$ | 30     | -          | -          | V             | $V_{GS}=0\text{ V}$ , $I_D=1\text{ mA}$                                                                                             |
| Gate threshold voltage           | $V_{GS(th)}$  | 1.2    | -          | 2          | V             | $V_{DS}=V_{GS}$ , $I_D=250\text{ }\mu\text{A}$                                                                                      |
| Zero gate voltage drain current  | $I_{DSS}$     | -      | 0.1<br>10  | 1<br>100   | $\mu\text{A}$ | $V_{DS}=30\text{ V}$ , $V_{GS}=0\text{ V}$ , $T_j=25\text{ °C}$<br>$V_{DS}=30\text{ V}$ , $V_{GS}=0\text{ V}$ , $T_j=125\text{ °C}$ |
| Gate-source leakage current      | $I_{GSS}$     | -      | 10         | 100        | nA            | $V_{GS}=20\text{ V}$ , $V_{DS}=0\text{ V}$                                                                                          |
| Drain-source on-state resistance | $R_{DS(on)}$  | -      | 2.0<br>1.6 | 2.5<br>1.9 | m $\Omega$    | $V_{GS}=4.5\text{ V}$ , $I_D=20\text{ A}$<br>$V_{GS}=10\text{ V}$ , $I_D=20\text{ A}$                                               |
| Gate resistance                  | $R_G$         | 0.4    | 0.8        | 1.6        | $\Omega$      | -                                                                                                                                   |
| Transconductance                 | $g_{fs}$      | 70     | 140        | -          | S             | $ V_{DS} >2 I_D R_{DS(on)max}$ , $I_D=30\text{ A}$                                                                                  |

**Table 5 Dynamic characteristics**

| Parameter                        | Symbol       | Values |      |      | Unit | Note / Test Condition                                                                              |
|----------------------------------|--------------|--------|------|------|------|----------------------------------------------------------------------------------------------------|
|                                  |              | Min.   | Typ. | Max. |      |                                                                                                    |
| Input capacitance <sup>1)</sup>  | $C_{iss}$    | -      | 2800 | 3800 | pF   | $V_{GS}=0\text{ V}$ , $V_{DS}=15\text{ V}$ , $f=1\text{ MHz}$                                      |
| Output capacitance <sup>1)</sup> | $C_{oss}$    | -      | 960  | 1300 | pF   | $V_{GS}=0\text{ V}$ , $V_{DS}=15\text{ V}$ , $f=1\text{ MHz}$                                      |
| Reverse transfer capacitance     | $C_{rss}$    | -      | 140  | -    | pF   | $V_{GS}=0\text{ V}$ , $V_{DS}=15\text{ V}$ , $f=1\text{ MHz}$                                      |
| Turn-on delay time               | $t_{d(on)}$  | -      | 5.4  | -    | ns   | $V_{DD}=15\text{ V}$ , $V_{GS}=10\text{ V}$ , $I_D=30\text{ A}$ ,<br>$R_{G,ext}=1.6\text{ }\Omega$ |
| Rise time                        | $t_r$        | -      | 6.8  | -    | ns   | $V_{DD}=15\text{ V}$ , $V_{GS}=10\text{ V}$ , $I_D=30\text{ A}$ ,<br>$R_{G,ext}=1.6\text{ }\Omega$ |
| Turn-off delay time              | $t_{d(off)}$ | -      | 28   | -    | ns   | $V_{DD}=15\text{ V}$ , $V_{GS}=10\text{ V}$ , $I_D=30\text{ A}$ ,<br>$R_{G,ext}=1.6\text{ }\Omega$ |
| Fall time                        | $t_f$        | -      | 4.6  | -    | ns   | $V_{DD}=15\text{ V}$ , $V_{GS}=10\text{ V}$ , $I_D=30\text{ A}$ ,<br>$R_{G,ext}=1.6\text{ }\Omega$ |

**Table 6 Gate charge characteristics<sup>2)</sup>**

| Parameter                           | Symbol        | Values |      |      | Unit | Note / Test Condition                                                        |
|-------------------------------------|---------------|--------|------|------|------|------------------------------------------------------------------------------|
|                                     |               | Min.   | Typ. | Max. |      |                                                                              |
| Gate to source charge <sup>1)</sup> | $Q_{gs}$      | -      | 7.0  | 9.3  | nC   | $V_{DD}=15\text{ V}$ , $I_D=30\text{ A}$ , $V_{GS}=0\text{ to }4.5\text{ V}$ |
| Gate charge at threshold            | $Q_{g(th)}$   | -      | 4.6  | -    | nC   | $V_{DD}=15\text{ V}$ , $I_D=30\text{ A}$ , $V_{GS}=0\text{ to }4.5\text{ V}$ |
| Gate to drain charge <sup>1)</sup>  | $Q_{gd}$      | -      | 6.5  | 8.5  | nC   | $V_{DD}=15\text{ V}$ , $I_D=30\text{ A}$ , $V_{GS}=0\text{ to }4.5\text{ V}$ |
| Switching charge                    | $Q_{sw}$      | -      | 9.0  | -    | nC   | $V_{DD}=15\text{ V}$ , $I_D=30\text{ A}$ , $V_{GS}=0\text{ to }4.5\text{ V}$ |
| Gate charge total <sup>1)</sup>     | $Q_g$         | -      | 22   | 29   | nC   | $V_{DD}=15\text{ V}$ , $I_D=30\text{ A}$ , $V_{GS}=0\text{ to }4.5\text{ V}$ |
| Gate plateau voltage                | $V_{plateau}$ | -      | 2.5  | -    | V    | $V_{DD}=15\text{ V}$ , $I_D=30\text{ A}$ , $V_{GS}=0\text{ to }4.5\text{ V}$ |
| Gate charge total <sup>1)</sup>     | $Q_g$         | -      | 44   | 59   | nC   | $V_{DD}=15\text{ V}$ , $I_D=30\text{ A}$ , $V_{GS}=0\text{ to }10\text{ V}$  |
| Gate charge total, sync. FET        | $Q_{g(sync)}$ | -      | 18   | -    | nC   | $V_{DS}=0.1\text{ V}$ , $V_{GS}=0\text{ to }4.5\text{ V}$                    |
| Output charge <sup>1)</sup>         | $Q_{oss}$     | -      | 25   | 33   | nC   | $V_{DD}=15\text{ V}$ , $V_{GS}=0\text{ V}$                                   |

<sup>1)</sup> Defined by design. Not subject to production test

<sup>2)</sup> See "Gate charge waveforms" for parameter definition

**Table 7 Reverse diode**

| Parameter                        | Symbol        | Values |      |      | Unit | Note / Test Condition                                              |
|----------------------------------|---------------|--------|------|------|------|--------------------------------------------------------------------|
|                                  |               | Min.   | Typ. | Max. |      |                                                                    |
| Diode continuous forward current | $I_S$         | -      | -    | 69   | A    | $T_C=25\text{ °C}$                                                 |
| Diode pulse current              | $I_{S,pulse}$ | -      | -    | 596  | A    | $T_C=25\text{ °C}$                                                 |
| Diode forward voltage            | $V_{SD}$      | -      | 0.8  | 1    | V    | $V_{GS}=0\text{ V}$ , $I_F=20\text{ A}$ , $T_j=25\text{ °C}$       |
| Reverse recovery charge          | $Q_{rr}$      | -      | 20   | -    | nC   | $V_R=15\text{ V}$ , $I_F=I_S$ , $di_F/dt=400\text{ A}/\mu\text{s}$ |

## 4 Electrical characteristics diagrams

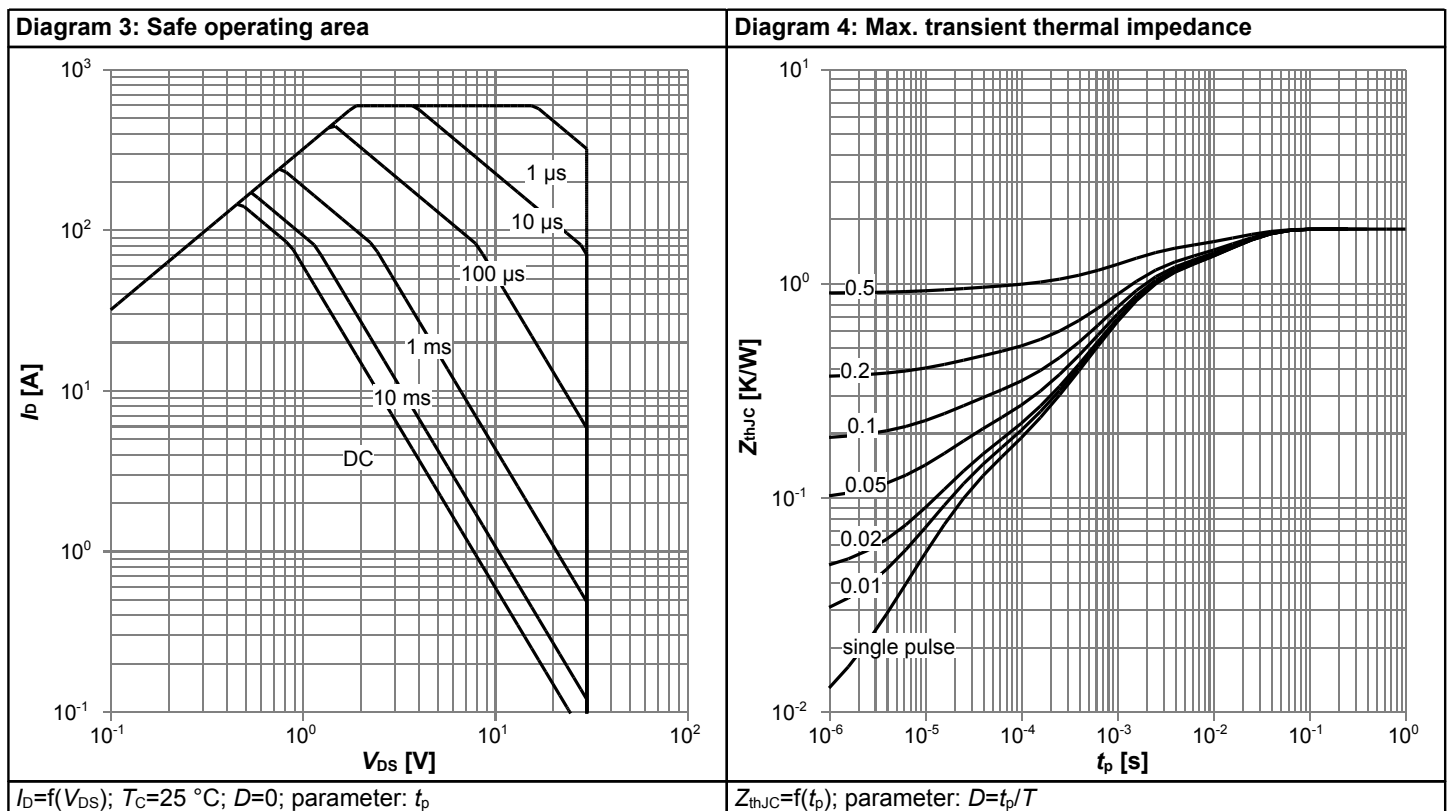
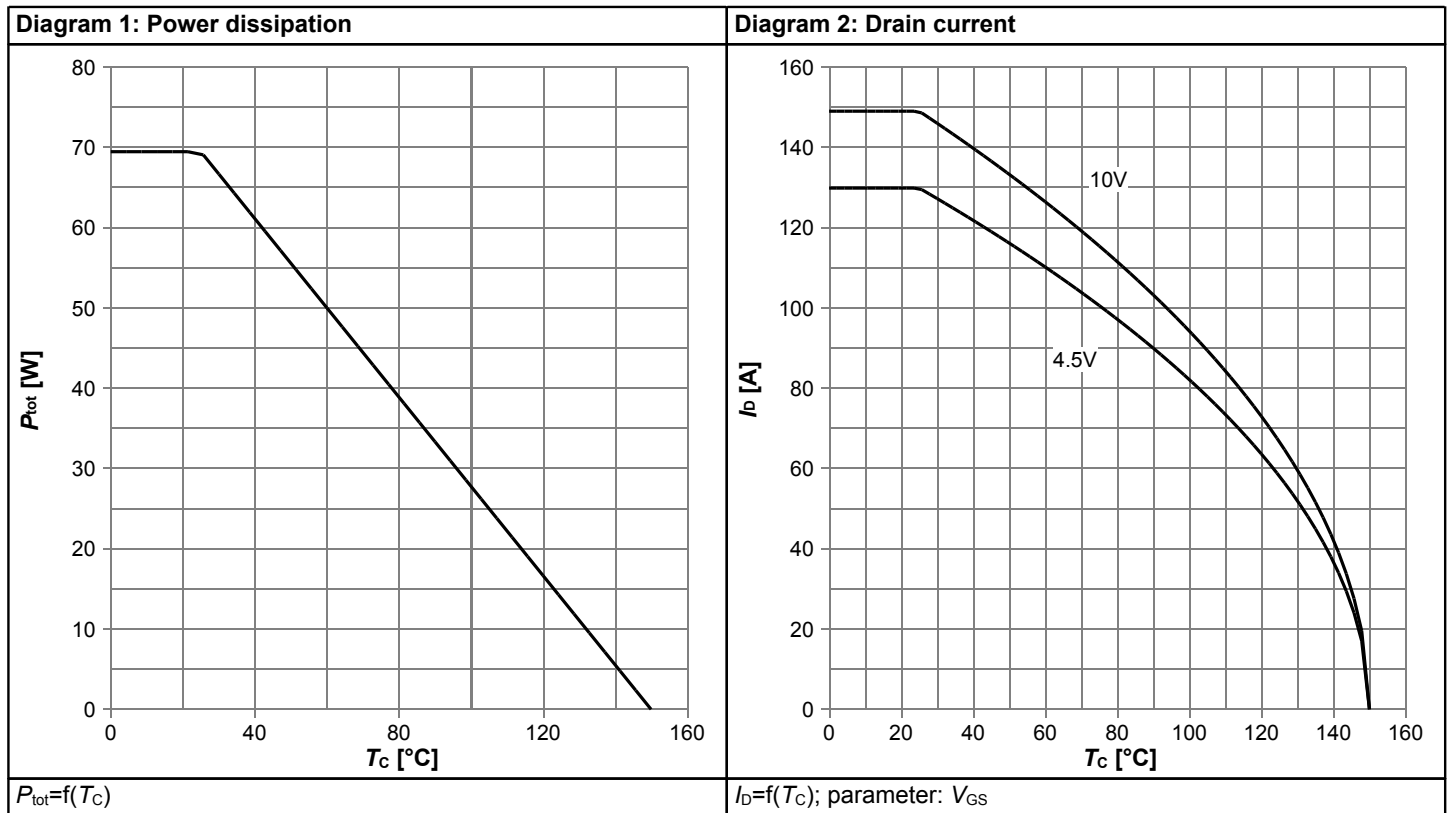
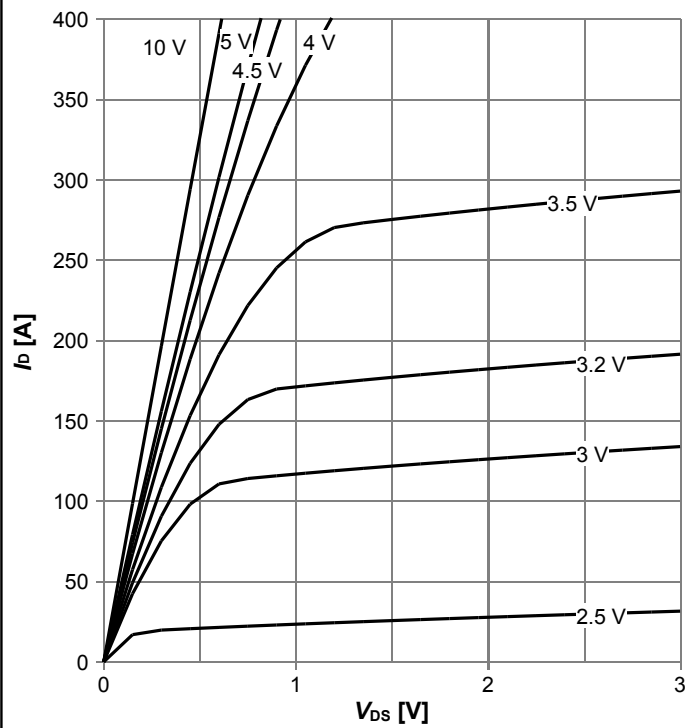
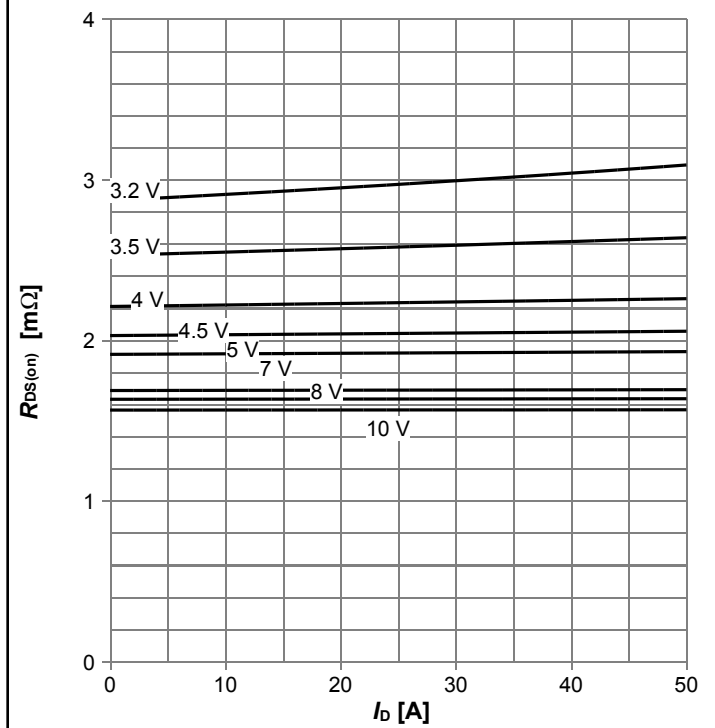


Diagram 5: Typ. output characteristics



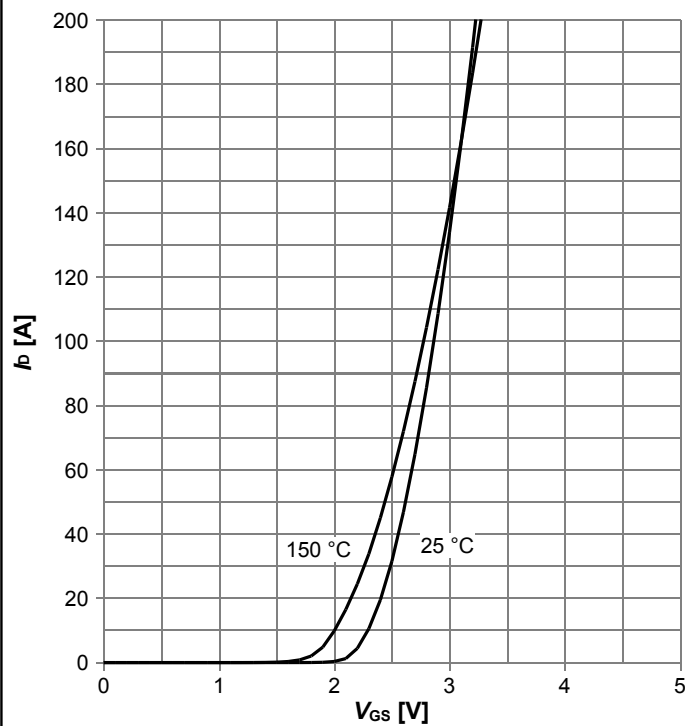
$I_D = f(V_{DS})$ ;  $T_j = 25^\circ\text{C}$ ; parameter:  $V_{GS}$

Diagram 6: Typ. drain-source on resistance



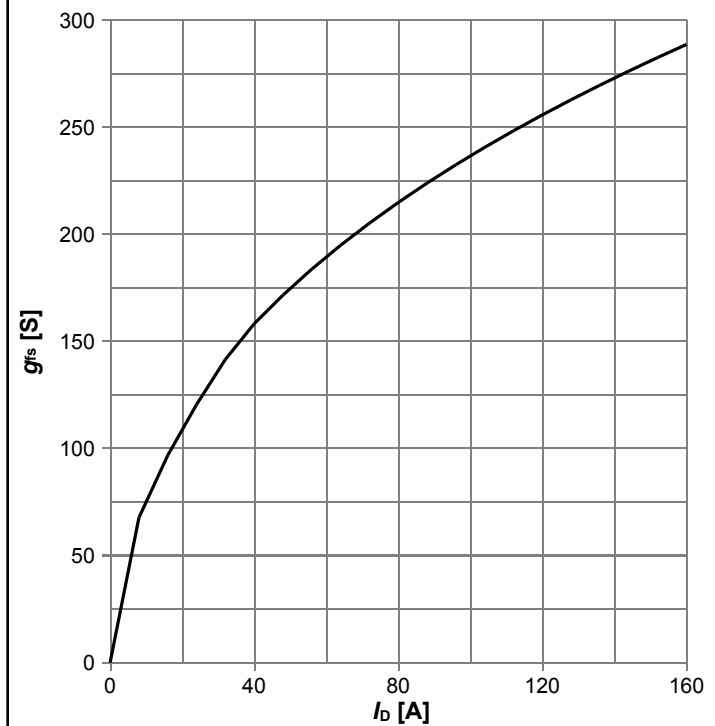
$R_{DS(on)} = f(I_D)$ ;  $T_j = 25^\circ\text{C}$ ; parameter:  $V_{GS}$

Diagram 7: Typ. transfer characteristics



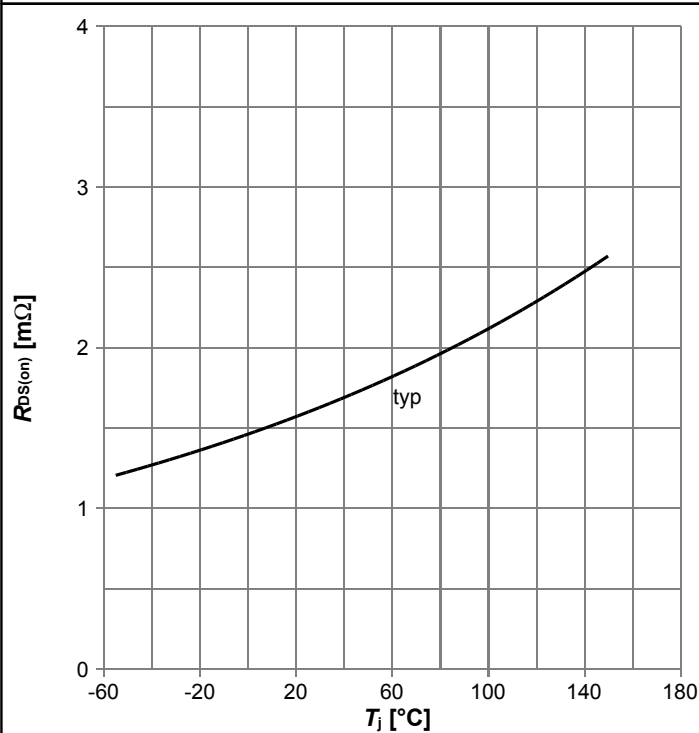
$I_D = f(V_{GS})$ ;  $|V_{DS}| > 2|I_D|R_{DS(on)max}$ ; parameter:  $T_j$

Diagram 8: Typ. forward transconductance



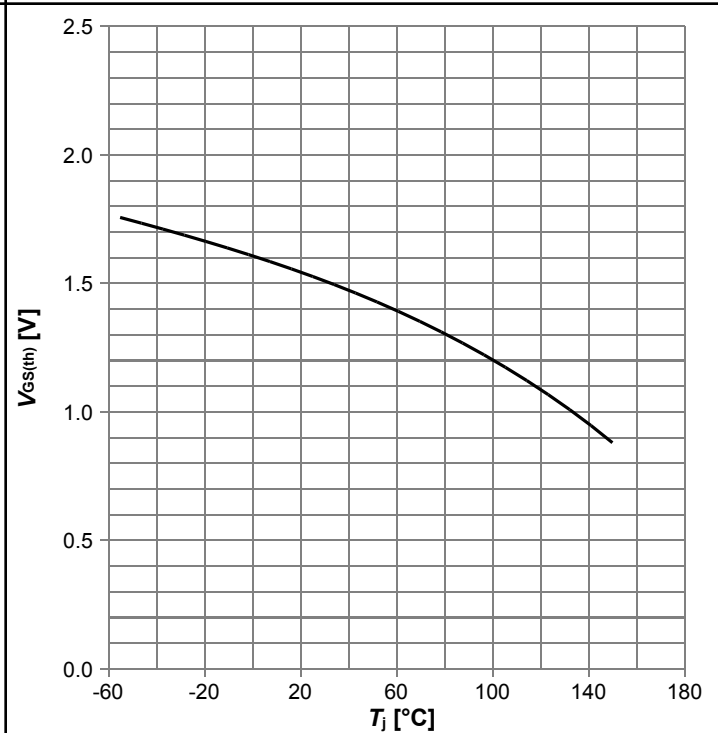
$g_{fs} = f(I_D)$ ;  $T_j = 25^\circ\text{C}$

Diagram 9: Drain-source on-state resistance



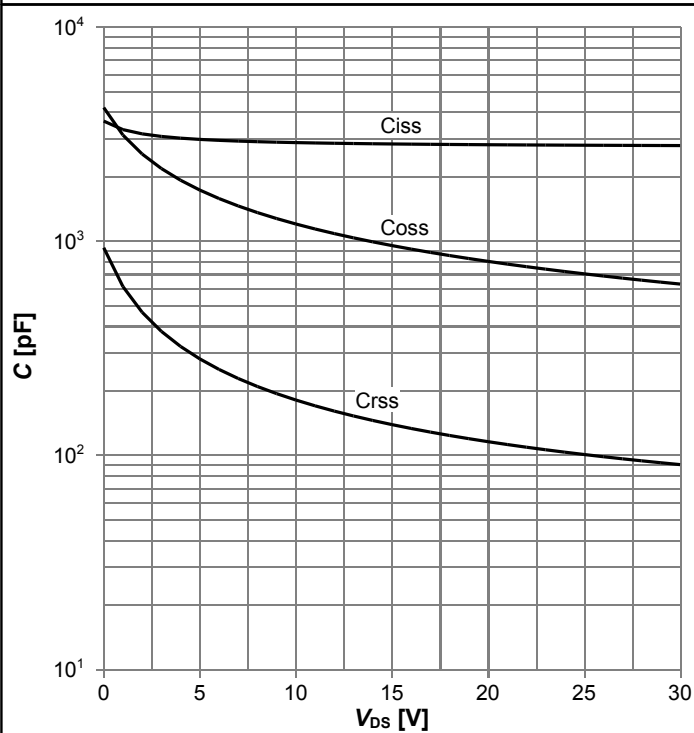
$R_{DS(on)} = f(T_j)$ ;  $I_D = 30 \text{ A}$ ;  $V_{GS} = 10 \text{ V}$

Diagram 10: Typ. gate threshold voltage



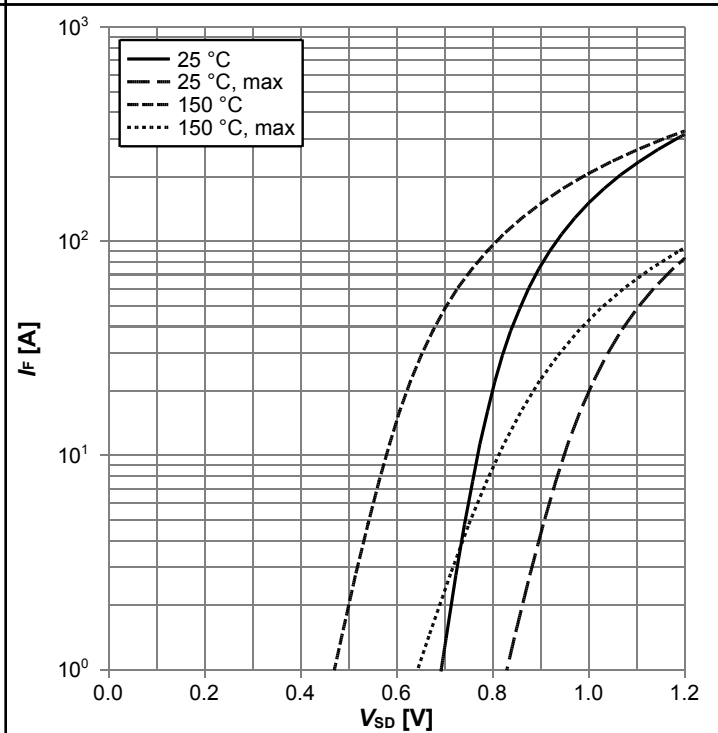
$V_{GS(th)} = f(T_j)$ ;  $V_{GS} = V_{DS}$ ;  $I_D = 250 \text{ μA}$

Diagram 11: Typ. capacitances



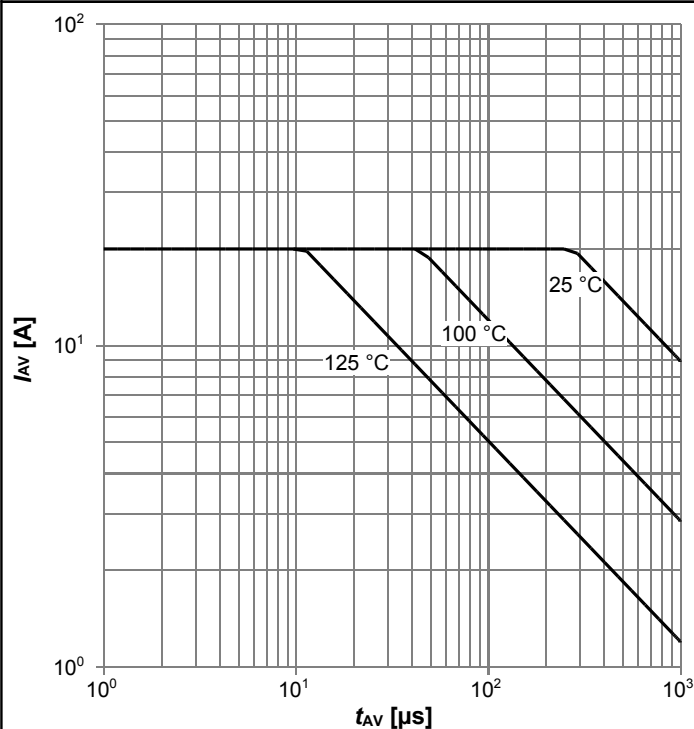
$C = f(V_{DS})$ ;  $V_{GS} = 0 \text{ V}$ ;  $f = 1 \text{ MHz}$

Diagram 12: Forward characteristics of reverse diode



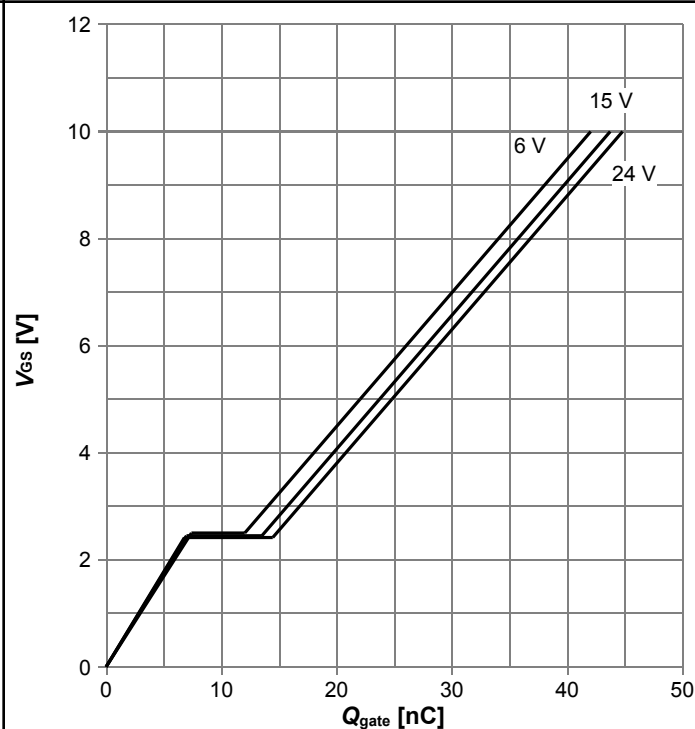
$I_F = f(V_{SD})$ ; parameter:  $T_j$

Diagram 13: Avalanche characteristics



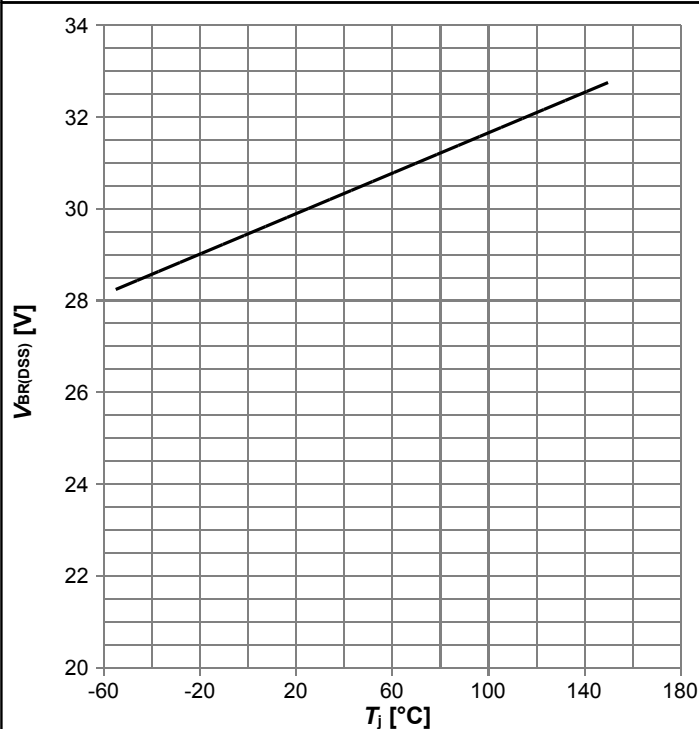
$I_{AS}=f(t_{AV})$ ;  $R_{GS}=25\ \Omega$ ; parameter:  $T_{j(start)}$

Diagram 14: Typ. gate charge



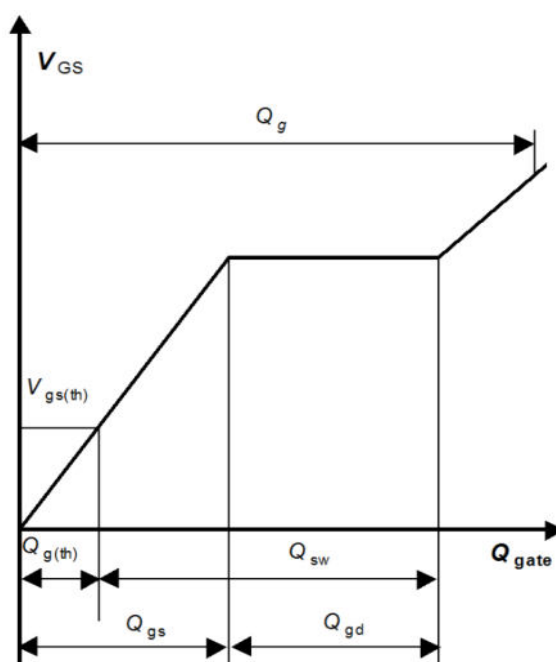
$V_{GS}=f(Q_{gate})$ ;  $I_D=30\text{ A}$  pulsed; parameter:  $V_{DD}$

Diagram 15: Drain-source breakdown voltage

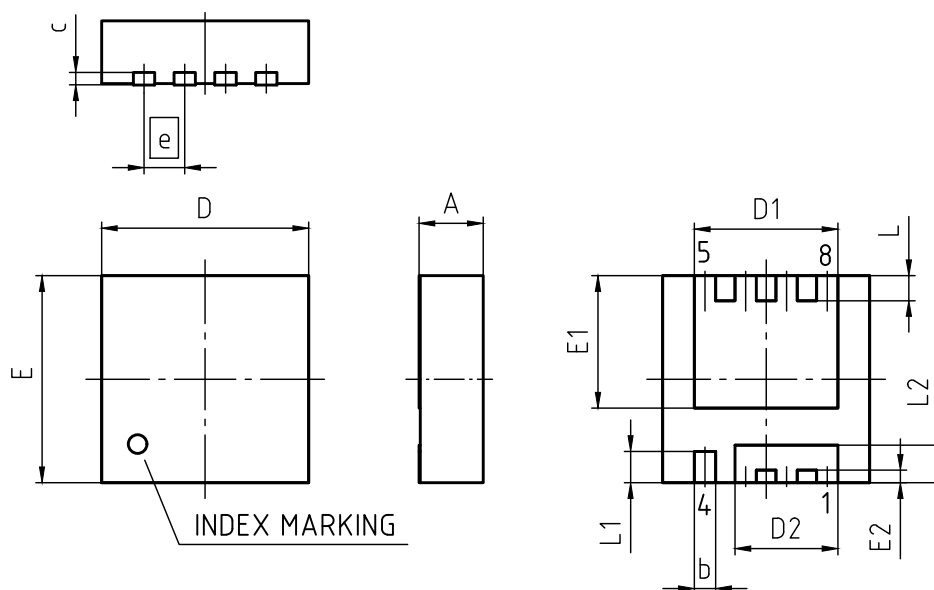


$V_{BR(DSS)}=f(T_j)$ ;  $I_D=1\text{ mA}$

Diagram Gate charge waveforms



## 5 Package Outlines



| PACKAGE - GROUP<br>NUMBER: <b>PG-TSDSON-8-U03</b> |             |                  |
|---------------------------------------------------|-------------|------------------|
| REVISION: 03                                      |             | DATE: 20.10.2020 |
| DIMENSIONS                                        | MILLIMETERS |                  |
|                                                   | MIN.        | MAX.             |
| <b>A</b>                                          | 0.90        | 1.10             |
| <b>b</b>                                          | 0.24        | 0.44             |
| <b>c</b>                                          | (0.20)      |                  |
| <b>D</b>                                          | 3.20        | 3.40             |
| <b>D1</b>                                         | 2.19        | 2.39             |
| <b>D2</b>                                         | 1.54        | 1.74             |
| <b>E</b>                                          | 3.20        | 3.40             |
| <b>E1</b>                                         | 2.01        | 2.21             |
| <b>E2</b>                                         | 0.10        | 0.30             |
| <b>e</b>                                          | 0.65        |                  |
| <b>L</b>                                          | 0.30        | 0.50             |
| <b>L1</b>                                         | 0.40        | 0.60             |
| <b>L2</b>                                         | 0.50        | 0.70             |
| <b>aaa</b>                                        | 0.06        |                  |

Figure 1 Outline PG-TSDSON-8 FL, dimensions in mm

## Revision History

BSZ019N03LS

**Revision: 2020-11-13, Rev. 2.4**

Previous Revision

| Revision | Date       | Subjects (major changes since last revision) |
|----------|------------|----------------------------------------------|
| 2.3      | 2020-08-12 | Update current rating and footnotes          |
| 2.4      | 2020-11-13 | Update package drawing                       |

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